flow 90PIM 1 — 1200V/25A

Features

- Trench Fieldstop Technology IGBT4 for low saturation loss
- Supports design with 90° mounting angle between heatsink and PCB
- Clip-in PCB mounting
- Clip or screw on heatsink mounting

Target Applications

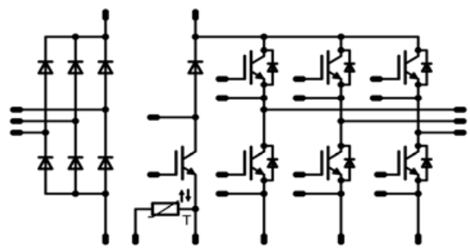
- Industrial drives

Types

- V23990-P630-A44-PM

flow 90PIM 1

Schematic



Maximum Ratings

T_j=25℃, unless otherwise specified

Parameter	Symbol	Condition		Value	Unit
Input Rectifier Diode					
Repetitive peak reverse voltage	V_{RRM}			1600	V
DC forward current	I_{FAV}	T_j=$T_j$max	T_h=80℃ T_c=80℃	27 37	A
Surge forward current	I_{FSM}	t_p=10ms	T_j=45℃	300	A
I^2t-value	I^2t			450	A^2s
Power dissipation per Diode	P_{tot}	T_j=$T_j$max	T_h=80℃ T_c=80℃	33 49	W
Maximum Junction Temperature	$T_j$max			150	℃

Parameter	Symbol	Condition		Value	Unit
Inverter Transistor					
Collector-emitter break down voltage	V_{CE}			1200	V
DC collector current	I_C	T_j=$T_j$max	T_h=80℃ T_c=80℃	29 37	A
Repetitive peak collector current	I_{Cpulse}	t_p limited by $T_j$max		75	A
Turn off safe operating area		VCE ≤ 1200V, Tj ≤ Top max		75	A
Power dissipation per IGBT	P_{tot}	T_j=$T_j$max	T_h=80℃ T_c=80℃	77 116	W
Gate-emitter peak voltage	V_{GE}			±20	V
Short circuit ratings	t_{SC} V_{CC}	T_j≤150℃ V_{GE}=15V		10 800	µs V
Maximum Junction Temperature	$T_j$max			175	℃

Maximum Ratings

T_j=25℃, unless otherwise specified

Parameter	Symbol	Condition		Value	Unit
Inverter FWD					
Peak Repetitive Reverse Voltage	V_{RRM}	T_j=25℃		1200	V
DC forward current	I_F	T_j=$T_j$max	T_h=80℃ T_c=80℃	27 35	A
Repetitive peak forward current	I_{FRM}	t_p limited by $T_j$max		50	A
Power dissipation per Diode	P_{tot}	T_j=$T_j$max	T_h=80℃ T_c=80℃	56 84	W
Maximum Junction Temperature	$T_j$max			175	℃
Brake Transistor					
Collector-emitter break down voltage	V_{CE}			1200	V
DC collector current	I_C	T_j=$T_j$max	T_h=80℃ T_c=80℃	20 26	A
Repetitive peak collector current	I_{Cpuls}	t_p limited by $T_j$max		45	A
Turn off safe operating area		V_{CE} ≤ 1200V, T_j ≤ $T_{op\ max}$		45	A
Power dissipation per IGBT	P_{tot}	T_j=$T_j$max	T_h=80℃ T_c=80℃	61 92	W
Gate-emitter peak voltage	V_{GE}			±20	V
Short circuit ratings	t_{SC} V_{CC}	T_j≤150℃ V_{GE}=15V		10 800	µs V
Maximum Junction Temperature	$T_j$max			175	℃
Brake FWD					
Peak Repetitive Reverse Voltage	V_{RRM}	T_j=25℃		1200	V
DC forward current	I_F	T_j=$T_j$max	T_h=80℃ T_c=80℃	20 20	A
Repetitive peak forward current	I_{FRM}	t_p limited by $T_j$max		20	A
Power dissipation per Diode	P_{tot}	T_j=$T_j$max	T_h=80℃ T_c=80℃	49 75	W
Maximum Junction Temperature	$T_j$max			175	℃
Thermal Properties					
Storage temperature	T_{stg}			-40…+125	℃
Operation temperature under switching condition	T_{op}			-40…+(Tjmax - 25)	℃
Insulation Properties					
Insulation voltage	V_{is}	t=2s	DC voltage	4000	V
Creepage distance				min 12,7	mm
Clearance				min 12,7	mm
Comparative tracking index	CTI			>200	

Characteristic Values

Parameter	Symbol	Conditions	V_{GE} [V] or V_{GS} [V]	V_r [V] or V_{CE} [V] or V_{DS} [V]	I_C [A] or I_F [A] or I_D [A]	T_j	Min	Typ	Max	Unit
Input Rectifier Diode										
Forward voltage	V_F				30	Tj=25℃ Tj=125℃	0,8	1,20 1,17	1,5	V
Threshold voltage (for power loss calc. only)	V_{to}				30	Tj=25℃ Tj=125℃		0,92 0,81		V
Slope resistance (for power loss calc. only)	r_t				30	Tj=25℃ Tj=125℃		11 14		mΩ
Reverse current	I_r			1600		Tj=25℃ Tj=125℃			0,01	mA
Thermal resistance chip to heatsink per chip	R_{thJH}	Thermal grease thickness≤50um λ = 1 W/mK						2,14		K/W
Inverter Transistor										
Gate emitter threshold voltage	$V_{GE(th)}$	$V_{CE}=V_{GE}$			0,00085	Tj=25℃ Tj=150℃	5	5,8	6,5	V
Collector-emitter saturation voltage	$V_{CE(sat)}$		15		25	Tj=25℃ Tj=150℃	1,6	1,96 2,30	2,1	V
Collector-emitter cut-off current incl. Diode	I_{CES}		0	1200		Tj=25℃ Tj=150℃			0,0024	mA
Gate-emitter leakage current	I_{GES}		20	0		Tj=25℃ Tj=150℃			120	nA
Integrated Gate resistor	R_{gint}							none		Ω
Turn-on delay time	$t_{d(on)}$	Rgoff=32 Ω Rgon=32 Ω	±15	600	25	Tj=25℃ Tj=150℃		127 130		ns
Rise time	t_r	Rgoff=32 Ω Rgon=32 Ω	±15	600	25	Tj=25℃ Tj=150℃		45 46		ns
Turn-off delay time	$t_{d(off)}$	Rgoff=32 Ω Rgon=32 Ω	±15	600	25	Tj=25℃ Tj=150℃		240 318		ns
Fall time	t_f	Rgoff=32 Ω Rgon=32 Ω	±15	600	25	Tj=25℃ Tj=150℃		68 136		ns
Turn-on energy loss per pulse	E_{on}	Rgoff=32 Ω Rgon=32 Ω	±15	600	25	Tj=25℃ Tj=150℃		2,61 3,77		mWs
Turn-off energy loss per pulse	E_{off}	Rgoff=32 Ω Rgon=32 Ω	±15	600	25	Tj=25℃ Tj=150℃		1,42 2,45		mWs
Input capacitance	C_{ies}	f=1MHz	0	25		Tj=25℃		1430		pF
Output capacitance	C_{oss}	f=1MHz	0	25		Tj=25℃		115		pF
Reverse transfer capacitance	C_{rss}	f=1MHz	0	25		Tj=25℃		85		pF
Gate charge	Q_{Gate}		±15	960	25	Tj=25℃		115		nC
Thermal resistance chip to heatsink per chip	R_{thJH}	Thermal grease thickness≤50um λ = 1 W/mK						1,24		K/W
Inverter FWD										
Diode forward voltage	V_F				25	Tj=25℃ Tj=150℃	1,35	1,86 1,81	2,05	V
Peak reverse recovery current	I_{RRM}	Rgon=32 Ω	±15	600	25	Tj=25℃ Tj=150℃		12 16		A
Reverse recovery time	t_{rr}	Rgon=32 Ω	±15	600	25	Tj=25℃ Tj=150℃		345 564		ns
Reverse recovered charge	Q_{rr}	Rgon=32 Ω	±15	600	25	Tj=25℃ Tj=150℃		2,18 4,68		µC
Peak rate of fall of recovery current	di(rec)max /dt	Rgon=32 Ω	±15	600	25	Tj=25℃ Tj=150℃		40 36		A/µs
Reverse recovered energy	Erec	Rgon=32 Ω	±15	600	25	Tj=25℃ Tj=150℃		0,77 1,74		mWs
Thermal resistance chip to heatsink per chip	R_{thJH}	Thermal grease thickness≤50um λ = 1 W/mK						1,71		K/W

Characteristic Values

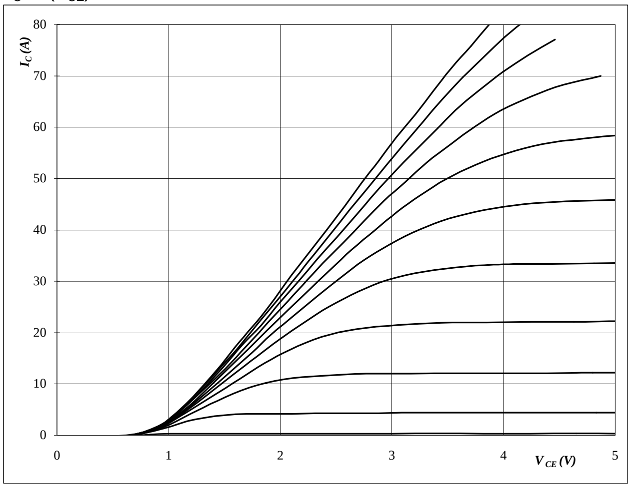
Parameter	Symbol	Conditions					Value			Unit
			V_{GE} [V] or V_{GS} [V]	V_r [V] or V_{CE} [V] or V_{DS} [V]	I_C [A] or I_F [A] or I_D [A]	T_j	Min	Typ	Max	
Brake Transistor										
Gate emitter threshold voltage	$V_{GE(th)}$	$V_{CE}=V_{GE}$			0,00043	Tj=25℃ Tj=150℃	5	5,8	6,5	V
Collector-emitter saturation voltage	$V_{CE(sat)}$		15		15	Tj=25℃ Tj=150℃	1,6	1,89 2,28	2,1	V
Collector-emitter cut-off incl diode	I_{CES}		0	1200		Tj=25℃ Tj=150℃			0,002	mA
Gate-emitter leakage current	I_{GES}		20	0		Tj=25℃ Tj=150℃			120	nA
Integrated Gate resistor	R_{gint}							none		Ω
Turn-on delay time	$t_{d(on)}$	Rgoff=32 Ω Rgon=32 Ω	±15	600	15	Tj=25℃ Tj=150℃		93 97		ns
Rise time	t_r					Tj=25℃ Tj=150℃		37 38		
Turn-off delay time	$t_{d(off)}$					Tj=25℃ Tj=150℃		199 267		
Fall time	t_f					Tj=25℃ Tj=150℃		80 131		
Turn-on energy loss per pulse	E_{on}					Tj=25℃ Tj=150℃		1,05 1,49		mWs
Turn-off energy loss per pulse	E_{off}					Tj=25℃ Tj=150℃		0,86 1,44		
Input capacitance	C_{ies}	f=1MHz	0	25		Tj=25℃		900		pF
Output capacitance	C_{oss}							80		
Reverse transfer capacitance	C_{rss}							55		
Gate charge	Q_{Gate}		±15	960	25	Tj=25℃		92		nC
Thermal resistance chip to heatsink per chip	R_{thJH}	Thermal grease thickness≤50um λ = 1 W/mK						1,56		K/W
Brake FWD										
Diode forward voltage	V_F				10	Tj=25℃ Tj=150℃	1,35	1,87 1,79	2,05	V
Reverse leakage current	I_r			1200		Tj=25℃ Tj=150℃			2,7	ǑA
Peak reverse recovery current	I_{RRM}	Rgon=32 Ω	±15	600	15	Tj=25℃ Tj=150℃		8 11		A
Reverse recovery time	t_{rr}					Tj=25℃ Tj=150℃		317 550		ns
Reverse recovered charge	Q_{rr}					Tj=25℃ Tj=150℃		1,20 1,20		µC
Peak rate of fall of recovery current	di(rec)max /dt					Tj=25℃ Tj=150℃		51 39		A/µs
Reverse recovery energy	E_{rec}					Tj=25℃ Tj=150℃		0,49 1,08		mWs
Thermal resistance chip to heatsink per chip	R_{thJH}	Thermal grease thickness≤50um λ = 1 W/mK						1,92		K/W
Thermistor										
Rated resistance	R					Tj=25℃		22000		Ω
Deviation of R100	ΔR/R	R100=1486 Ω				Tc=100℃	-5		5	%
Power dissipation	P					Tc=25℃		200		mW
Power dissipation constant						Tj=25℃		2		mW/K
B-value	$B_{(25/50)}$	Tol. ±3%				Tj=25℃		3950		K
B-value	$B_{(25/100)}$	Tol. ±3%				Tj=25℃		3996		K
Vincotech NTC Reference									B	

Output Inverter

Figure 1 Output inverter IGBT

Typical output characteristics

$I_C = f(V_{CE})$



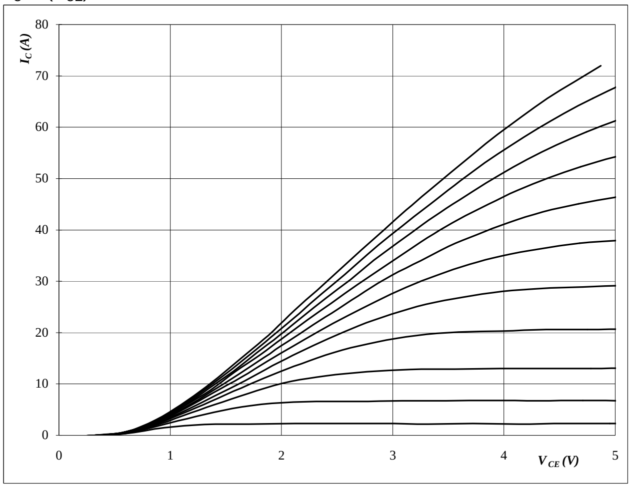
At

t_p =	250	Ǒs
T_j =	25	℃
V_{GE} from	7 V to 17 V in steps of 1 V	

Figure 2 Output inverter IGBT

Typical output characteristics

$I_C = f(V_{CE})$



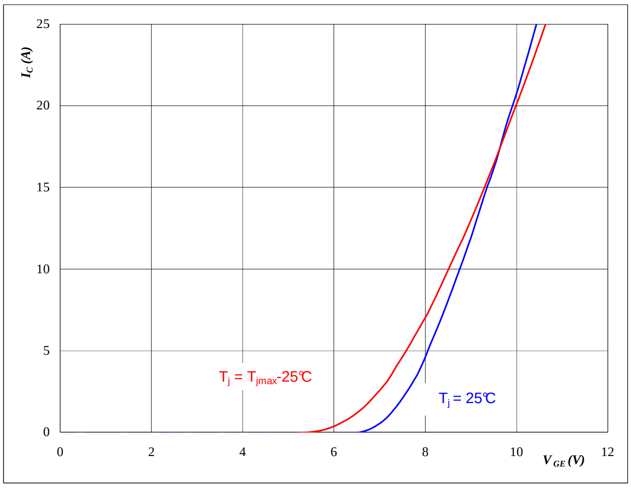
At

t_p =	250	Ǒs
T_j =	150	℃
V_{GE} from	7 V to 17 V in steps of 1 V	

Figure 3 Output inverter IGBT

Typical transfer characteristics

$I_C = f(V_{GE})$



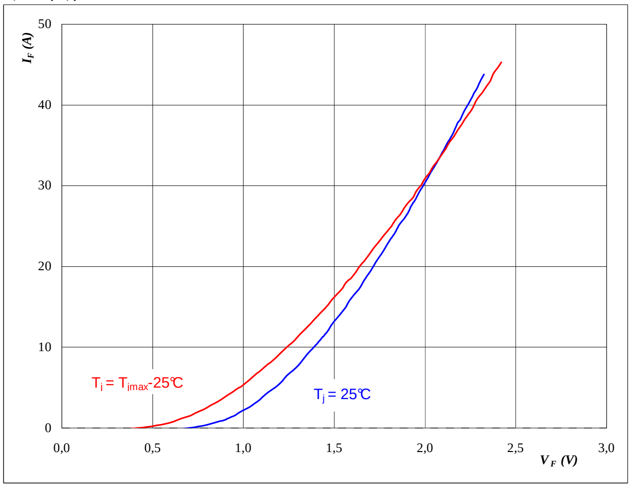
At

t_p =	250	Ǒs
V_{CE} =	10	V

Figure 4 Output inverter FWD

Typical diode forward current as a function of forward voltage

$I_F = f(V_F)$



At

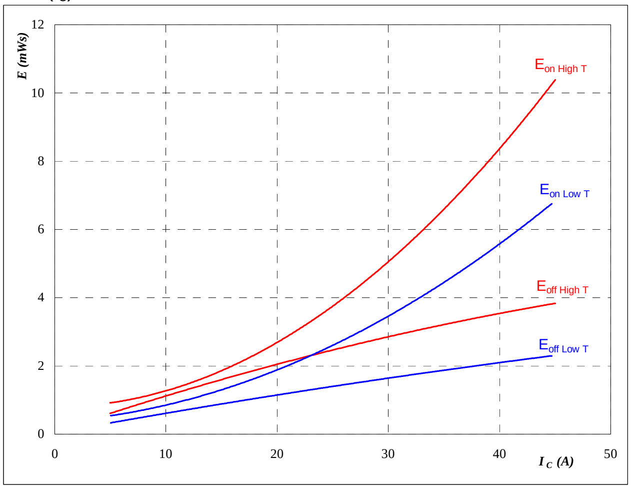
t_p =	250	Ǒs

Output Inverter

Figure 5 Output inverter IGBT

Typical switching energy losses
as a function of collector current

$E = f(I_C)$



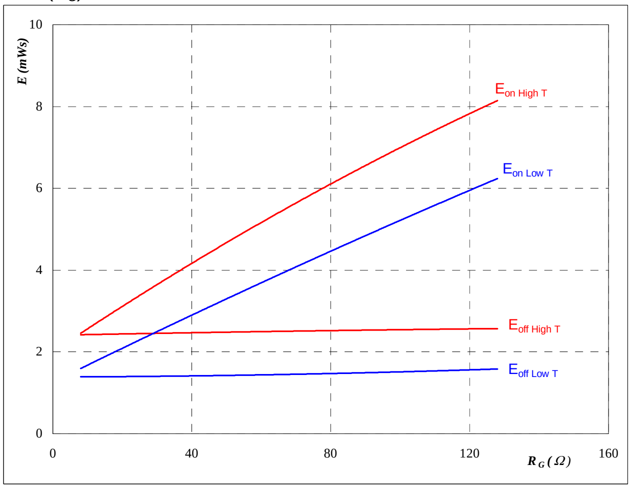
With an inductive load at

T_j =	25/150	°C
V_{CE} =	600	V
V_{GE} =	±15	V
R_{gon} =	32	Ω
R_{goff} =	32	Ω

Figure 6 Output inverter IGBT

Typical switching energy losses
as a function of gate resistor

$E = f(R_G)$



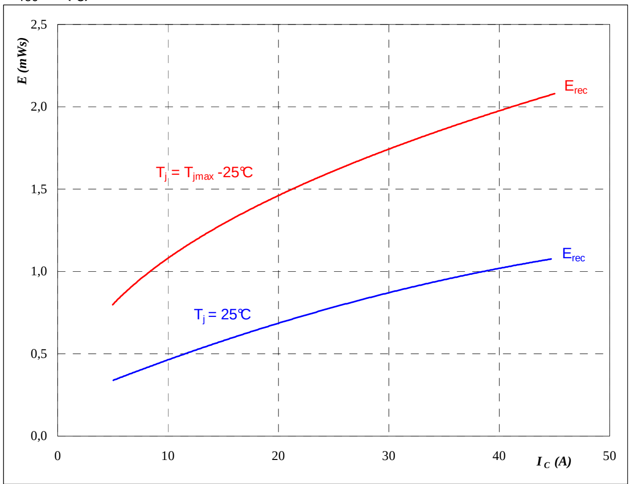
With an inductive load at

T_j =	25/150	°C
V_{CE} =	600	V
V_{GE} =	±15	V
I_C =	25	A

Figure 7 Output inverter FWD

Typical reverse recovery energy loss
as a function of collector current

$E_{rec} = f(I_C)$



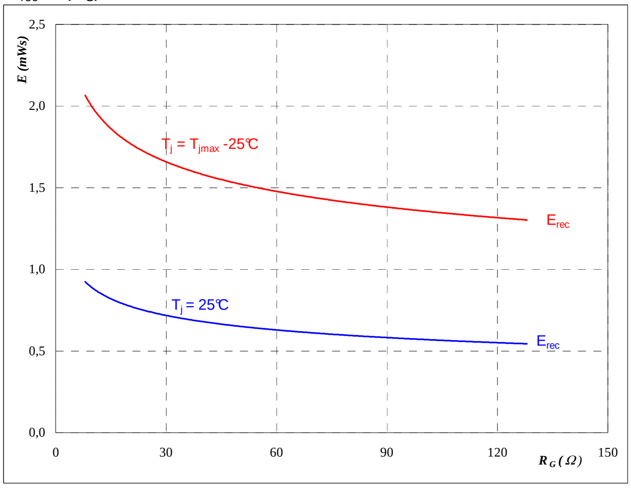
With an inductive load at

T_j =	25/150	°C
V_{CE} =	600	V
V_{GE} =	±15	V
R_{gon} =	32	Ω

Figure 8 Output inverter FWD

Typical reverse recovery energy loss
as a function of gate resistor

$E_{rec} = f(R_G)$



With an inductive load at

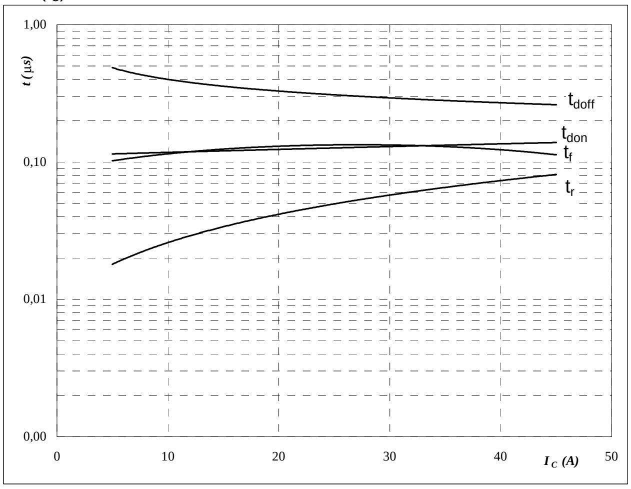
T_j =	25/150	°C
V_{CE} =	600	V
V_{GE} =	±15	V
I_C =	25	A

Output Inverter

Figure 9 Output inverter IGBT

Typical switching times as a function of collector current

t = f(I_C)



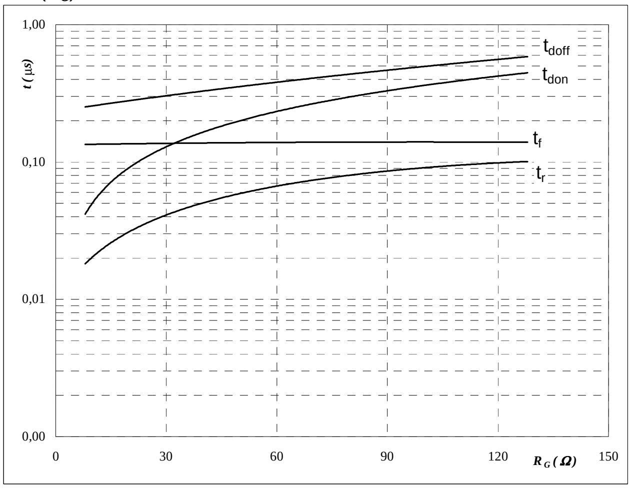
With an inductive load at

T_j =	150	°C
V_{CE} =	600	V
V_{GE} =	±15	V
R_{gon} =	32	Ω
R_{goff} =	32	Ω

Figure 10 Output inverter IGBT

Typical switching times as a function of gate resistor

t = f(R_G)



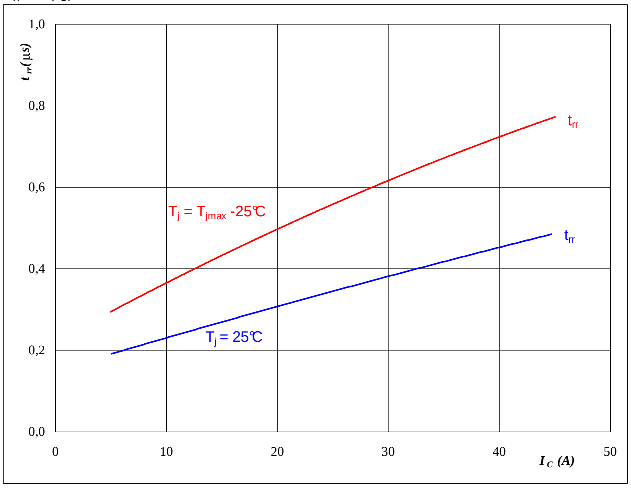
With an inductive load at

T_j =	150	°C
V_{CE} =	600	V
V_{GE} =	±15	V
I_C =	25	A

Figure 11 Output inverter FWD

Typical reverse recovery time as a function of collector current

t_{rr} = f(I_C)



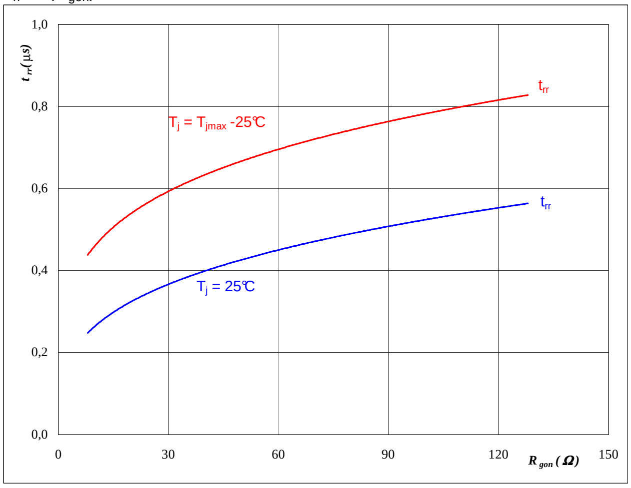
At

T_j =	25/150	°C
V_{CE} =	600	V
V_{GE} =	±15	V
R_{gon} =	32	Ω

Figure 12 Output inverter FWD

Typical reverse recovery time as a function of IGBT turn on gate resistor

t_{rr} = f(R_{gon})



At

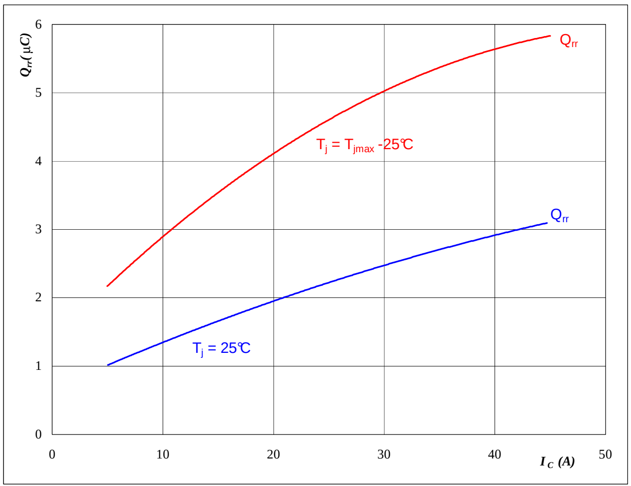
T_j =	25/150	°C
V_R =	600	V
I_F =	25	A
V_{GE} =	±15	V

Output Inverter

Figure 13 Output inverter FWD

Typical reverse recovery charge as a function of collector current

$Q_{rr} = f(I_C)$



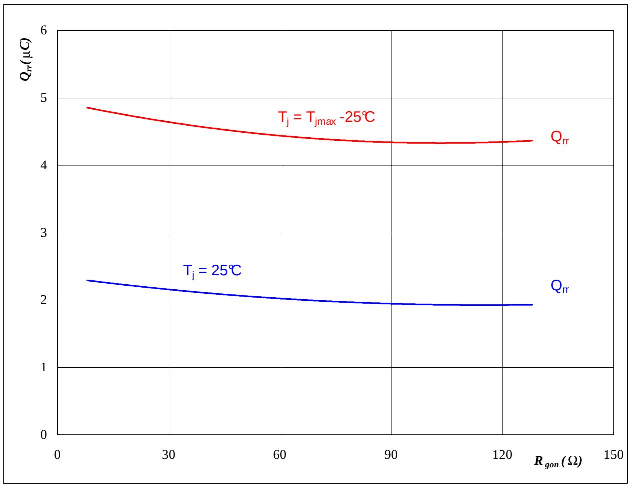
At

T_j =	25/150	℃
V_{CE} =	600	V
V_{GE} =	±15	V
R_{gon} =	32	Ω

Figure 14 Output inverter FWD

Typical reverse recovery charge as a function of IGBT turn on gate resistor

$Q_{rr} = f(R_{gon})$



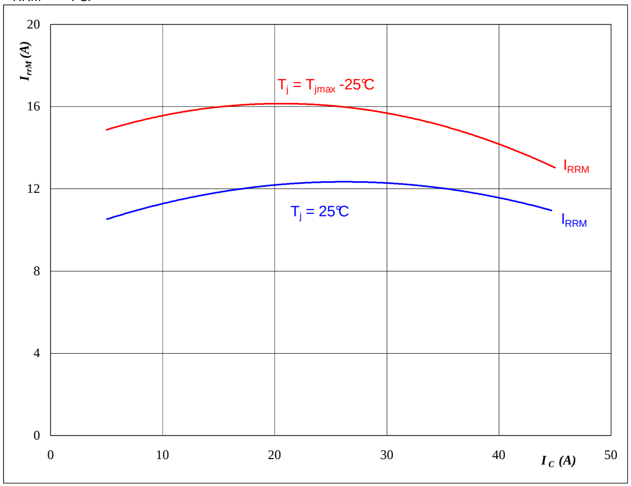
At

T_j =	25/150	℃
V_R =	600	V
I_F =	25	A
V_{GE} =	±15	V

Figure 15 Output inverter FWD

Typical reverse recovery current as a function of collector current

$I_{RRM} = f(I_C)$



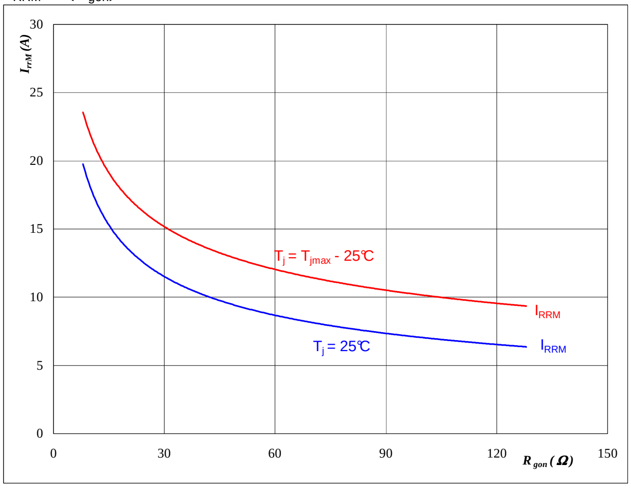
At

T_j =	25/150	℃
V_{CE} =	600	V
V_{GE} =	±15	V
R_{gon} =	32	Ω

Figure 16 Output inverter FWD

Typical reverse recovery current as a function of IGBT turn on gate resistor

$I_{RRM} = f(R_{gon})$



At

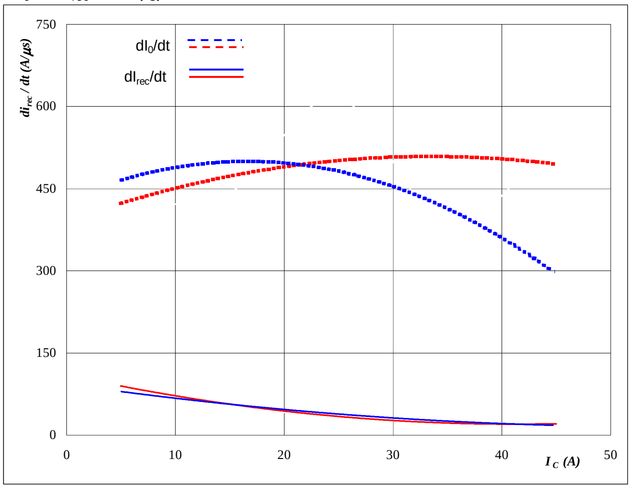
T_j =	25/150	℃
V_R =	600	V
I_F =	25	A
V_{GE} =	±15	V

Output Inverter

Figure 17	Output inverter FWD

Typical rate of fall of forward and reverse recovery current as a function of collector current

$dI_0/dt, dI_{rec}/dt = f(I_C)$



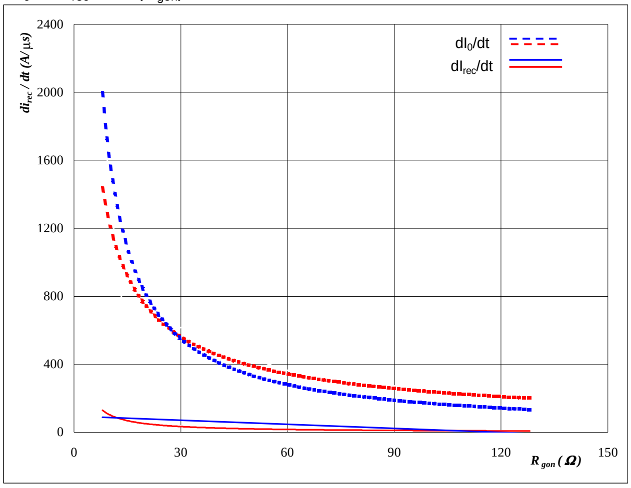
At

T_j =	25/150	°C
V_{CE} =	600	V
V_{GE} =	±15	V
R_{gon} =	32	Ω

Figure 18	Output inverter FWD

Typical rate of fall of forward and reverse recovery current as a function of IGBT turn on gate resistor

$dI_0/dt, dI_{rec}/dt = f(R_{gon})$



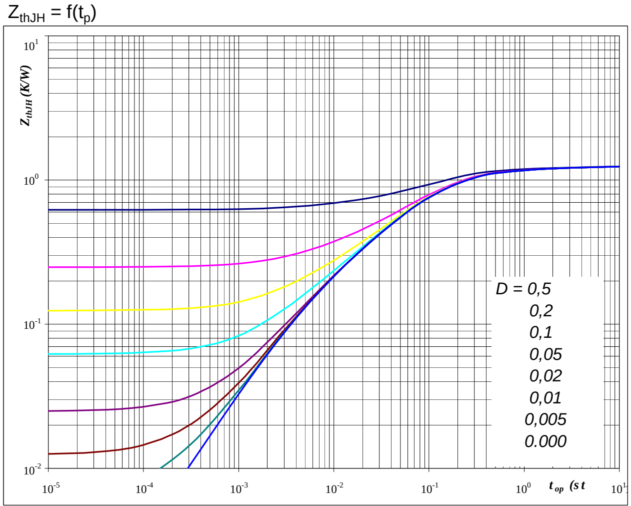
At

T_j =	25/150	°C
V_R =	600	V
I_F =	25	A
V_{GE} =	±15	V

Figure 19	Output inverter IGBT

IGBT transient thermal impedance as a function of pulse width

$Z_{thJH} = f(t_p)$



At

D =	t_p / T			
R_{thJH} =	1,24	K/W	RthJH =	1,01

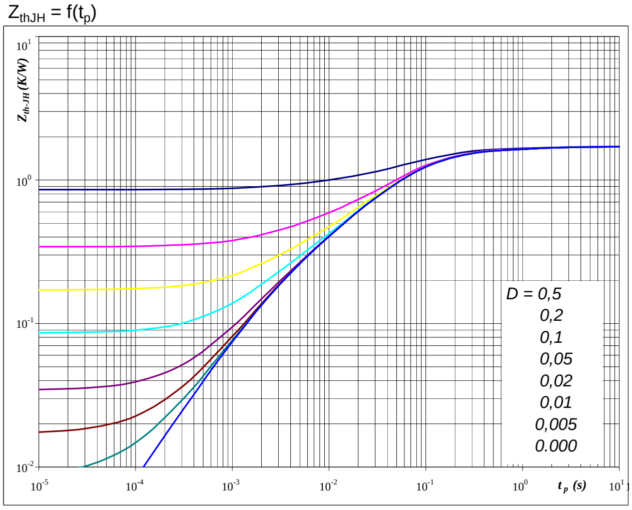
IGBT thermal model values

Thermal grease R (C/W)	Thermal grease Tau (s)	Phase change interface R (C/W)	Phase change interface Tau (s)
0,09	2,4E+00	0,07	2,0E+00
0,17	4,2E-01	0,14	3,4E-01
0,66	1,1E-01	0,53	8,8E-02
0,24	2,6E-02	0,20	2,1E-02
0,08	4,3E-03	0,07	3,5E-03

Figure 20	Output inverter FWD

FWD transient thermal impedance as a function of pulse width

$Z_{thJH} = f(t_p)$



At

D =	t_p / T			
R_{thJH} =	1,71	K/W	RthJH =	1,39

FWD thermal model values

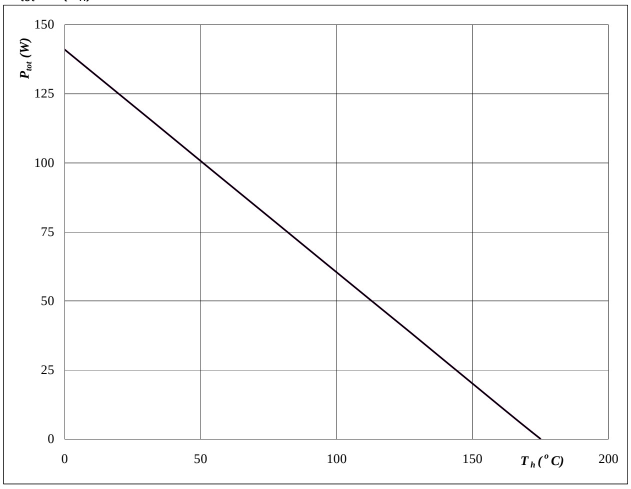
Thermal grease R (C/W)	Thermal grease Tau (s)	Phase change interface R (C/W)	Phase change interface Tau (s)
0,03	6,7E+00	0,03	5,5E+00
0,11	1,0E+00	0,09	8,3E-01
0,36	1,7E-01	0,29	1,4E-01
0,87	5,6E-02	0,70	4,6E-02
0,24	1,1E-02	0,19	9,2E-03
0,10	2,3E-03	0,08	1,8E-03

Output Inverter

Figure 21 Output inverter IGBT

Power dissipation as a function of heatsink temperature

$P_{tot} = f(T_h)$



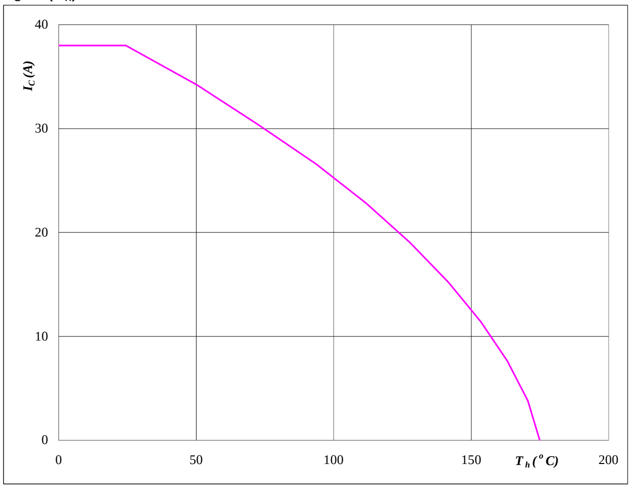
At

T_j = 175 ℃

Figure 22 Output inverter IGBT

Collector current as a function of heatsink temperature

$I_C = f(T_h)$



At

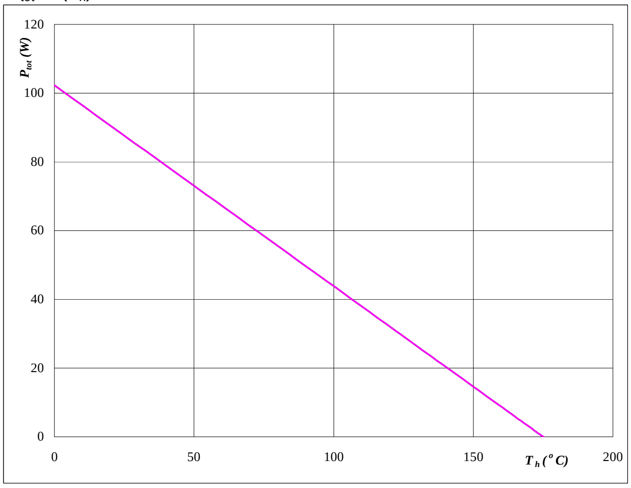
T_j = 175 ℃

V_{GE} = 15 V

Figure 23 Output inverter FWD

Power dissipation as a function of heatsink temperature

$P_{tot} = f(T_h)$



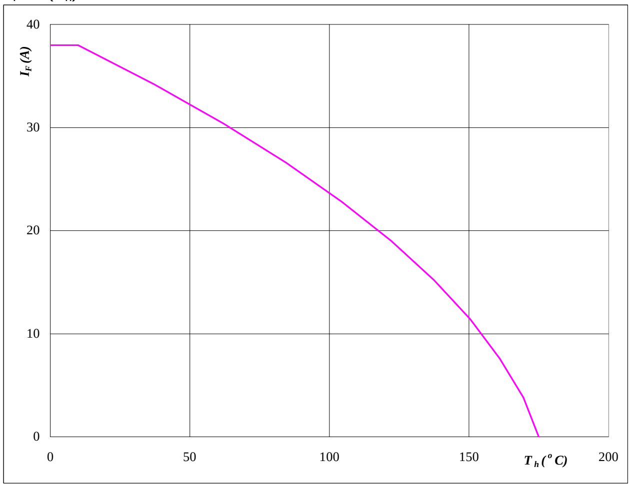
At

T_j = 175 ℃

Figure 24 Output inverter FWD

Forward current as a function of heatsink temperature

$I_F = f(T_h)$



At

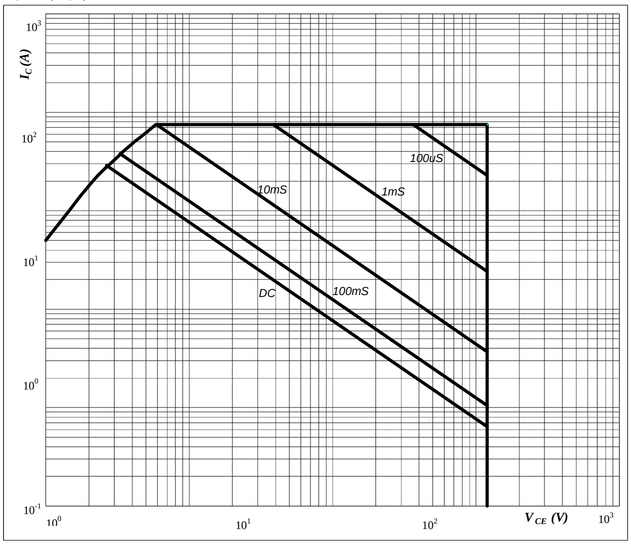
T_j = 175 ℃

Output Inverter

Figure 25 Output inverter IGBT

Safe operating area as a function of collector-emitter voltage

$I_C = f(V_{CE})$



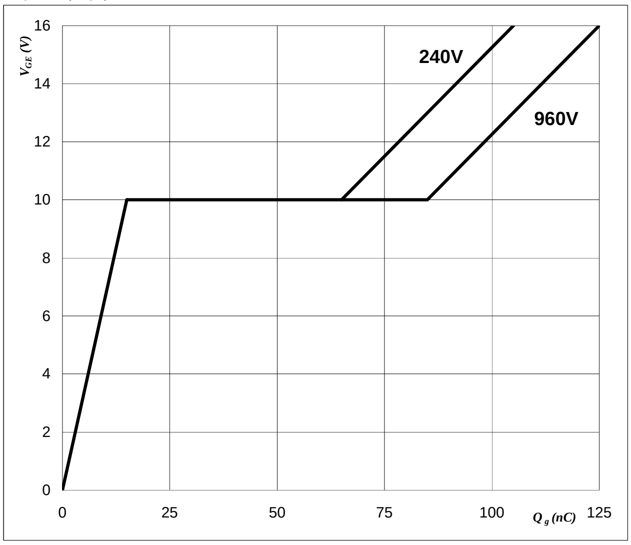
At

D =	single pulse	
T_h =	80	ºC
V_{GE} =	±15	V
T_j =	T_{jmax}	ºC

Figure 26 Output inverter IGBT

Gate voltage vs Gate charge

$V_{GE} = f(Q_{GE})$



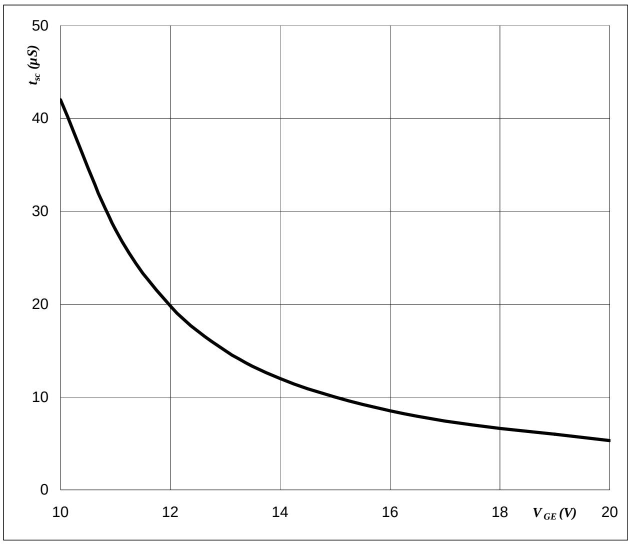
At

I_C =	25	A

Figure 27 Output inverter IGBT

Short circuit withstand time as a function of gate-emitter voltage

$t_{sc} = f(V_{GE})$



At

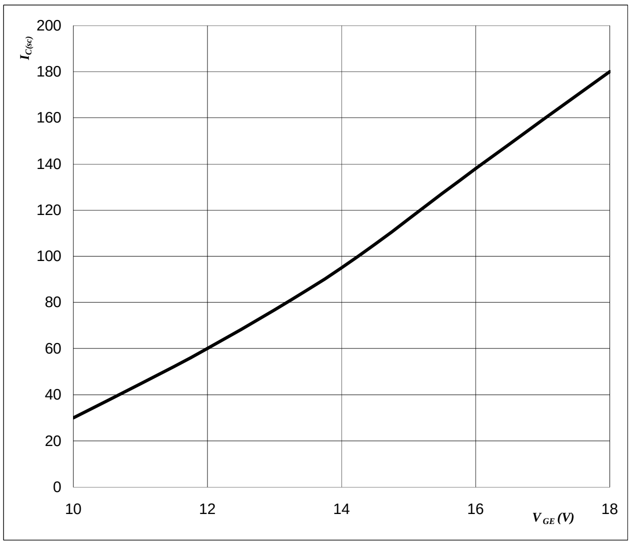
V_{CE} = 1200 V

T_j ≤ 175 ºC

Figure 28 Output inverter IGBT

Typical short circuit collector current as a function of gate-emitter voltage

$V_{GE} = f(Q_{GE})$



At

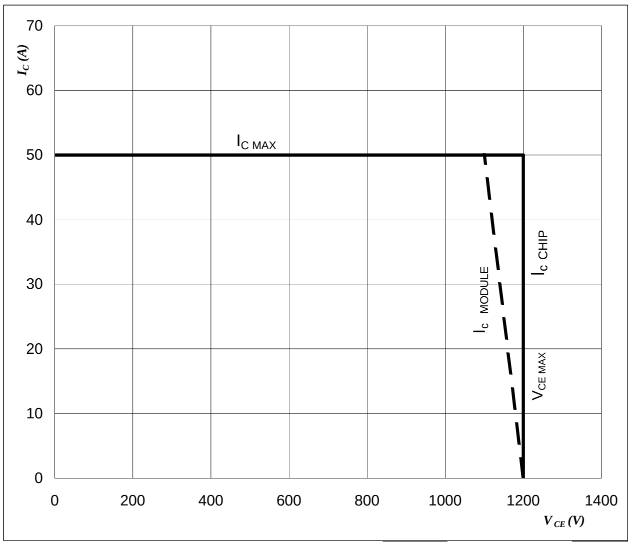
V_{CE} ≤ 1200 V

T_j = 175 ºC

Figure 29 IGBT

Reverse bias safe operating area

$I_C = f(V_{CE})$



At

T_j = T_{jmax}-25 ºC

$U_{ccminus}$=U_{ccplus}

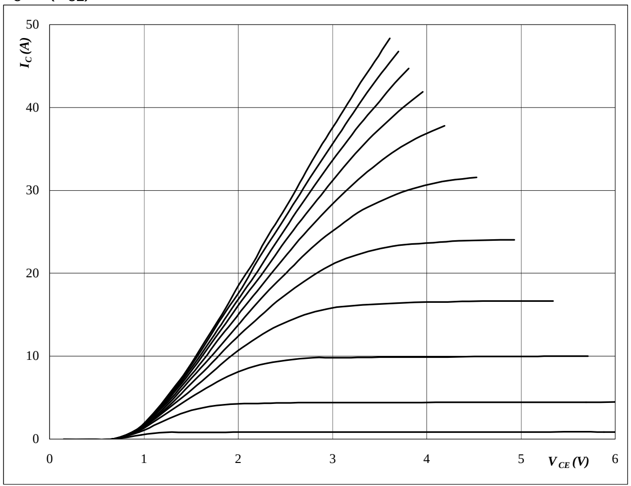
Switching mode : 3phase SPWM

Brake

Figure 1 Brake IGBT

Typical output characteristics

$I_C = f(V_{CE})$



At

t_p = 250 Ős

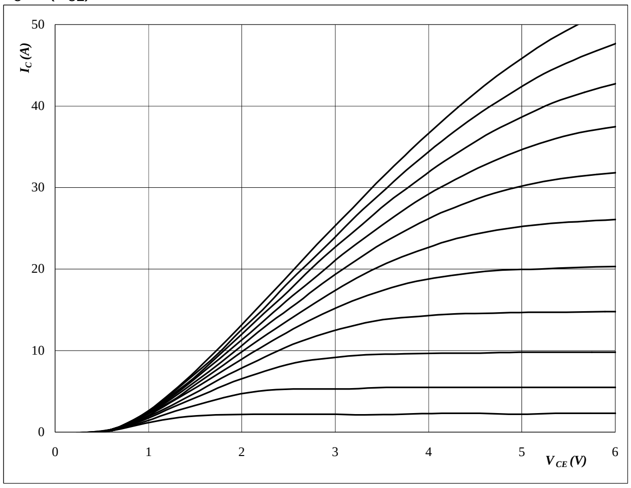
T_j = 25 ℃

V_{GE} from 7 V to 17 V in steps of 1 V

Figure 2 Brake IGBT

Typical output characteristics

$I_C = f(V_{CE})$



At

t_p = 250 Ős

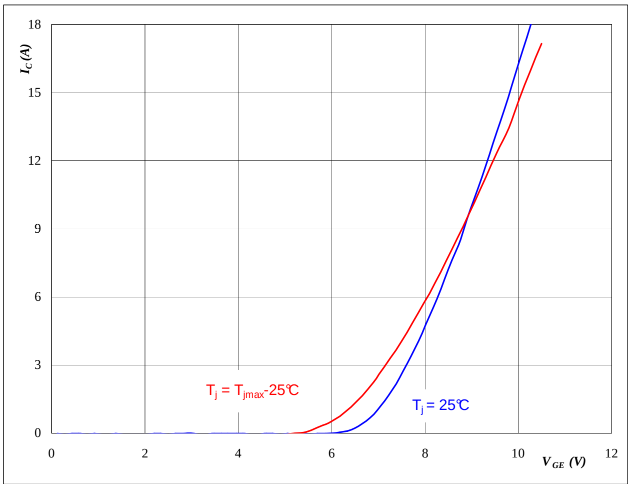
T_j = 150 ℃

V_{GE} from 7 V to 17 V in steps of 1 V

Figure 3 Brake IGBT

Typical transfer characteristics

$I_C = f(V_{GE})$



At

t_p = 250 Ős

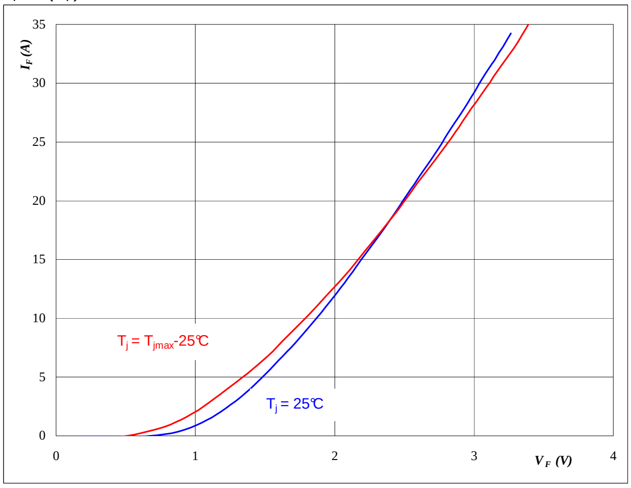
V_{CE} = 10 V

Figure 4 Brake FWD

Typical diode forward current as

a function of forward voltage

$I_F = f(V_F)$



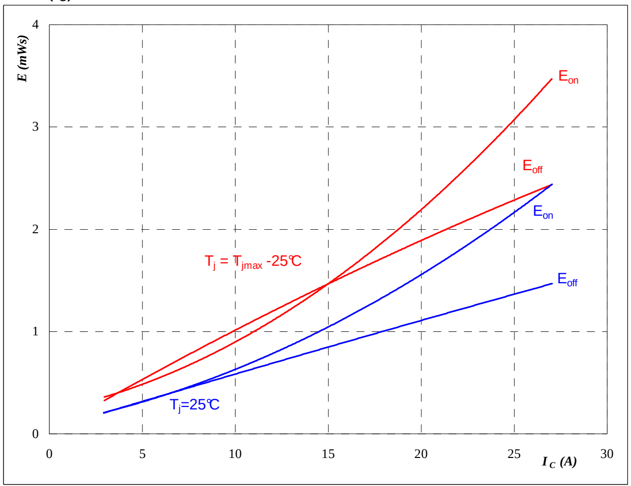
At

t_p = 250 Ős

Brake

Figure 5 Brake IGBT

Typical switching energy losses
as a function of collector current
$E = f(I_C)$

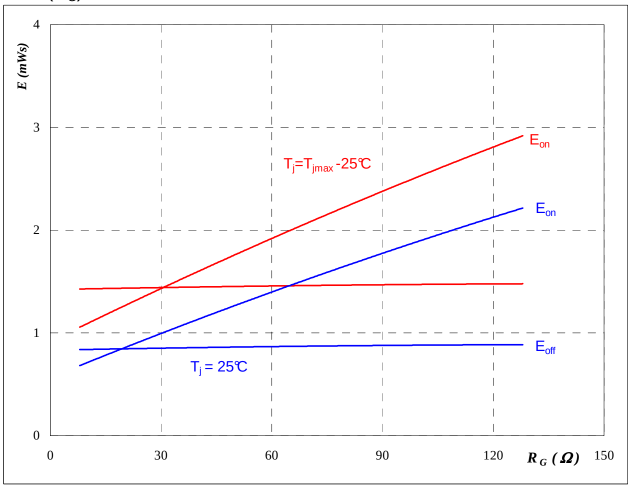


With an inductive load at

T_j =	25/150	℃
V_{CE} =	600	V
V_{GE} =	±15	V
R_{gon} =	32	Ω
R_{goff} =	32	Ω

Figure 6 Brake IGBT

Typical switching energy losses
as a function of gate resistor
$E = f(R_G)$

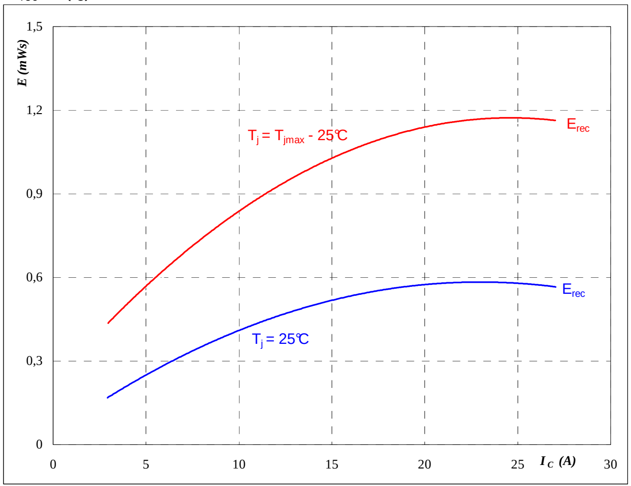


With an inductive load at

T_j =	25/150	℃
V_{CE} =	600	V
V_{GE} =	±15	V
I_C =	15	A

Figure 7 Brake FWD

Typical reverse recovery energy loss
as a function of collector current
$E_{rec} = f(I_C)$

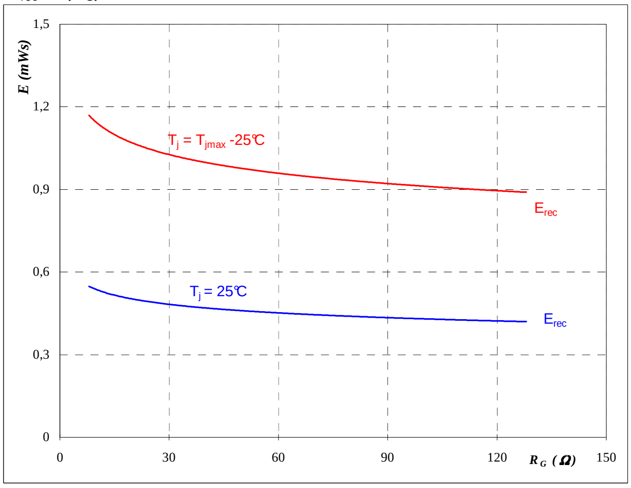


With an inductive load at

T_j =	25/150	℃
V_{CE} =	600	V
V_{GE} =	±15	V
R_{gon} =	32	Ω

Figure 8 Brake FWD

Typical reverse recovery energy loss
as a function of gate resistor
$E_{rec} = f(R_G)$



With an inductive load at

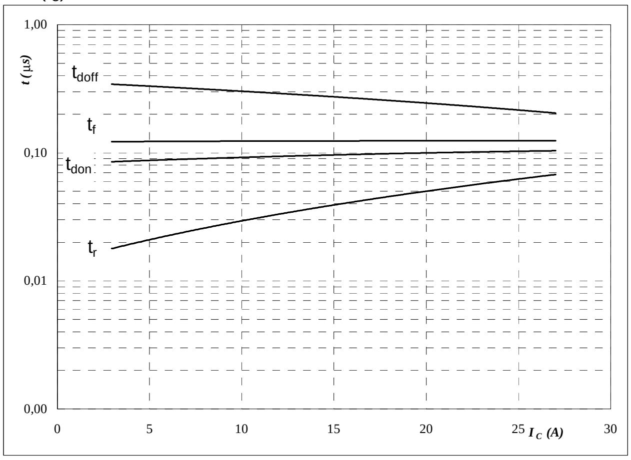
T_j =	25/150	℃
V_{CE} =	600	V
V_{GE} =	±15	V
I_C =	15	A

Brake

Figure 9 Brake IGBT

Typical switching times as a function of collector current

t = f(I_C)



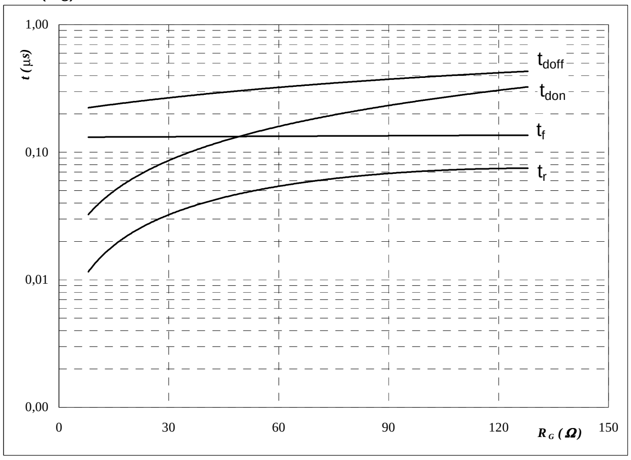
With an inductive load at

T_j =	25/150	℃
V_{CE} =	600	V
V_{GE} =	±15	V
R_{gon} =	32	Ω
R_{goff} =	32	Ω

Figure 10 Brake IGBT

Typical switching times as a function of gate resistor

t = f(R_G)



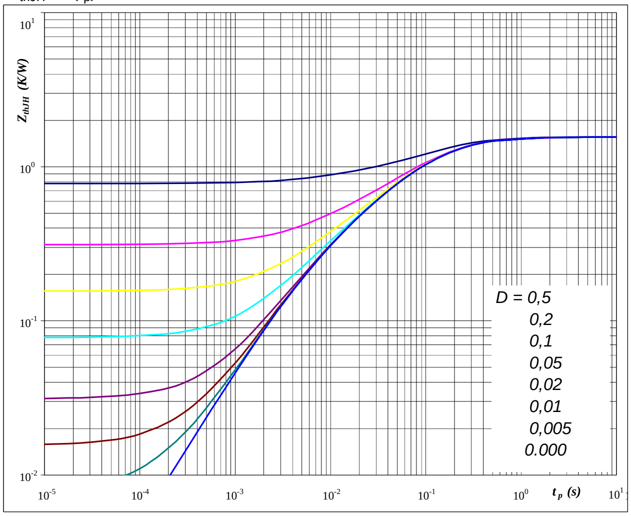
With an inductive load at

T_j =	25/150	℃
V_{CE} =	600	V
V_{GE} =	±15	V
I_C =	15	A

Figure 11 Brake IGBT

IGBT transient thermal impedance as a function of pulse width

Z_{thJH} = f(t_p)



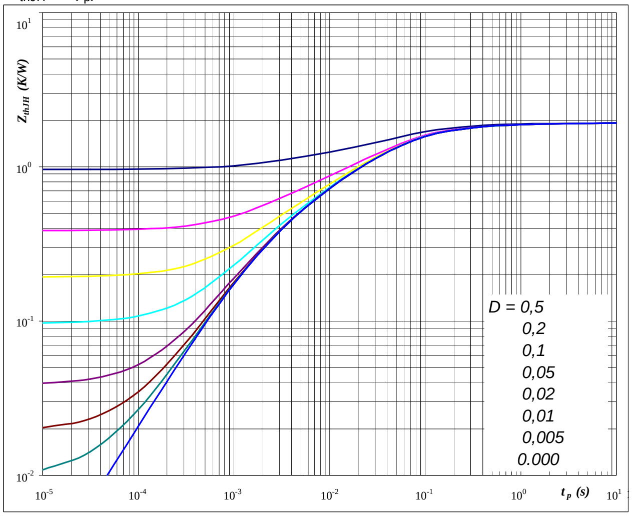
At D = tp / T

Thermal grease			Phase change interface		
R_{thJH} =	1,56	K/W	R_{thJH} =	1,26	K/W

Figure 12 Brake FWD

FWD transient thermal impedance as a function of pulse width

Z_{thJH} = f(t_p)



At D = tp / T

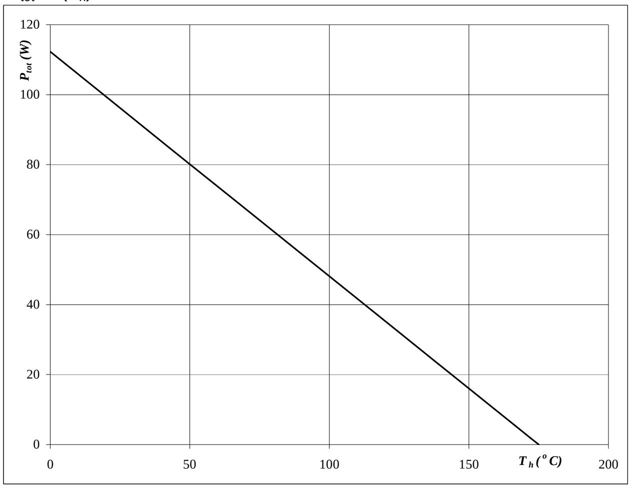
Thermal grease			Phase change interface		
R_{thJH} =	1,92	K/W	R_{thJH} =	1,56	K/W

Brake

Figure 13 Brake IGBT

Power dissipation as a function of heatsink temperature

$P_{tot} = f(T_h)$



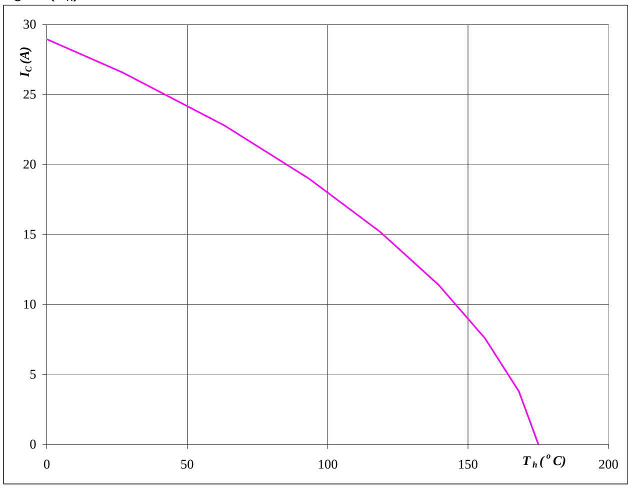
At

T_j = 175 ºC

Figure 14 Brake IGBT

Collector current as a function of heatsink temperature

$I_C = f(T_h)$



At

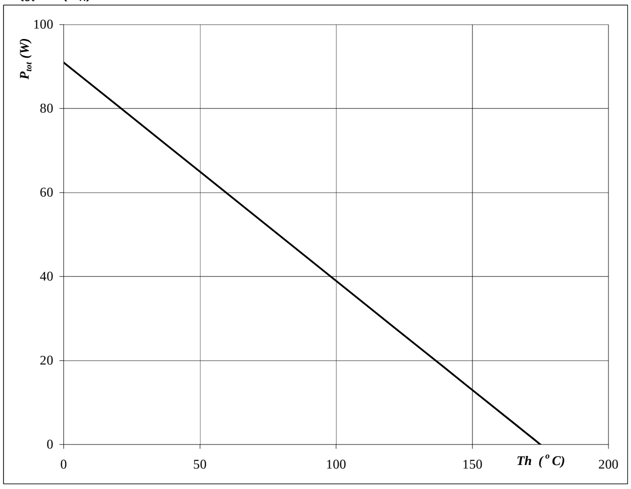
T_j = 175 ºC

V_{GE} = 15 V

Figure 15 Brake FWD

Power dissipation as a function of heatsink temperature

$P_{tot} = f(T_h)$



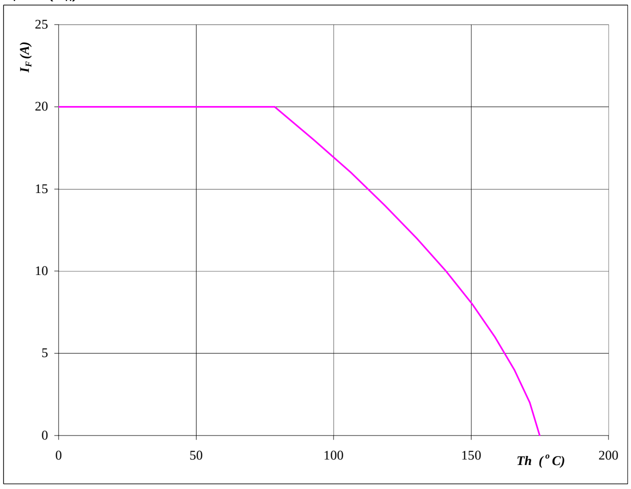
At

T_j = 175 ºC

Figure 16 Brake FWD

Forward current as a function of heatsink temperature

$I_F = f(T_h)$



At

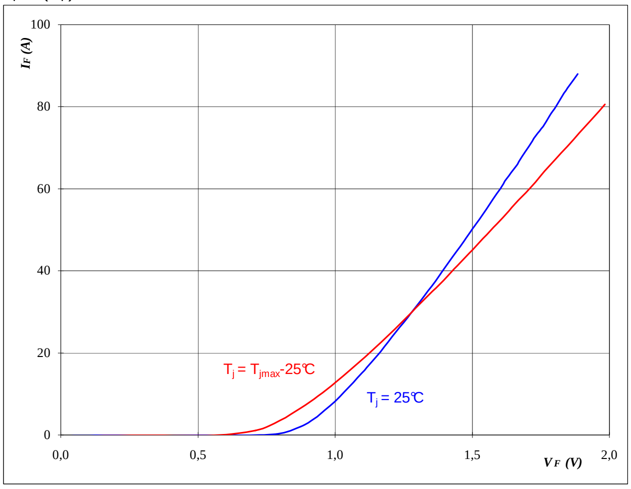
T_j = 175 ºC

Input Rectifier Bridge

Figure 1 Rectifier diode

Typical diode forward current as a function of forward voltage

$I_F = f(V_F)$



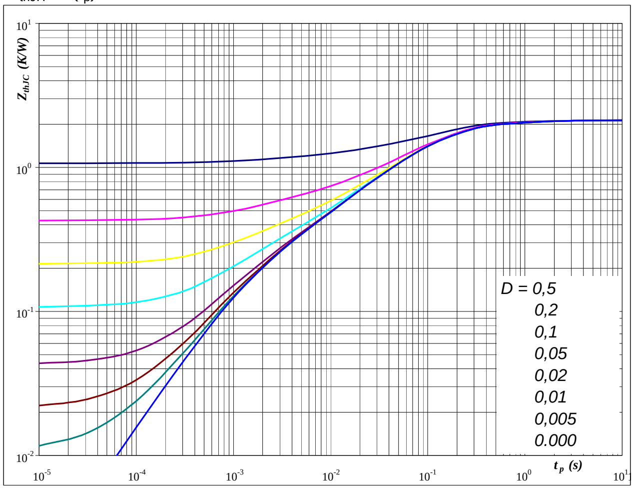
At

t_p = 250 Ǒs

Figure 2 Rectifier diode

Diode transient thermal impedance as a function of pulse width

$Z_{thJH} = f(t_p)$



At

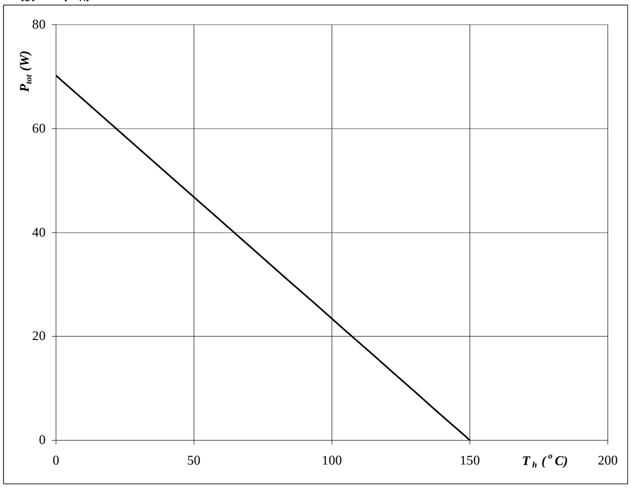
D = t_p / T

R_{thJH} = 2,14 K/W

Figure 3 Rectifier diode

Power dissipation as a function of heatsink temperature

$P_{tot} = f(T_h)$



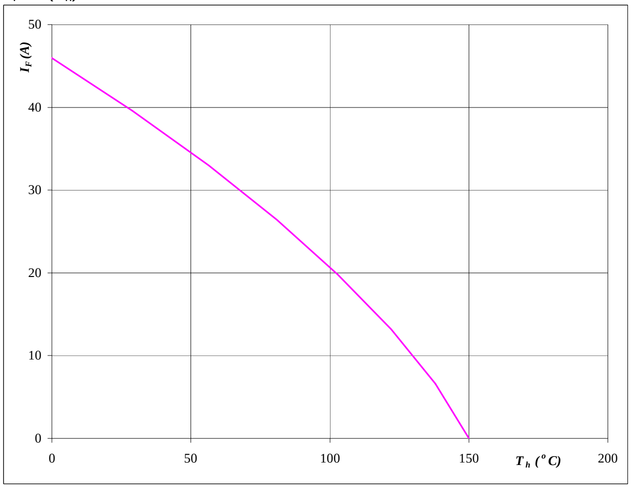
At

T_j = 150 ºC

Figure 4 Rectifier diode

Forward current as a function of heatsink temperature

$I_F = f(T_h)$



At

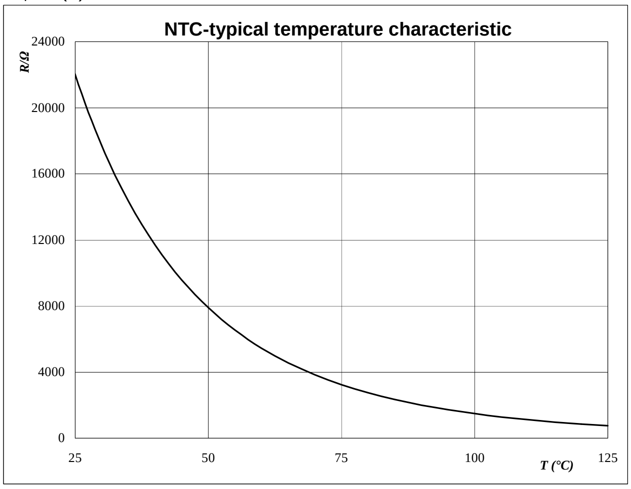
T_j = 150 ºC

Thermistor

Figure 1 Thermistor

Typical NTC characteristic
as a function of temperature

$R_T = f(T)$



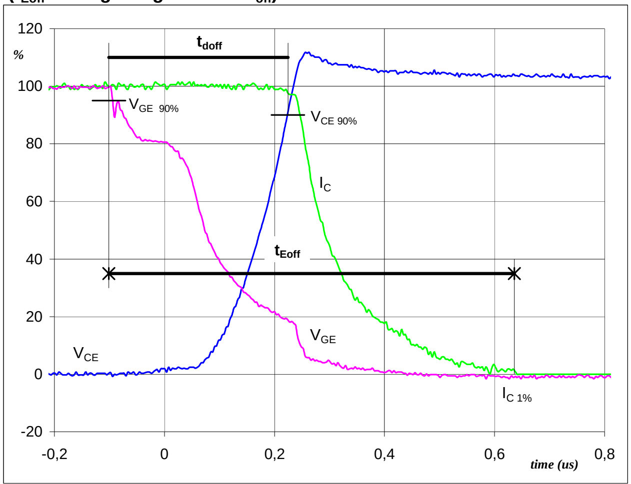
Switching Definitions Output Inverter

General conditions

T_j	=	150 ℃
R_{gon}	=	32 Ω
R_{goff}	=	32 Ω

Figure 1 Output inverter IGBT

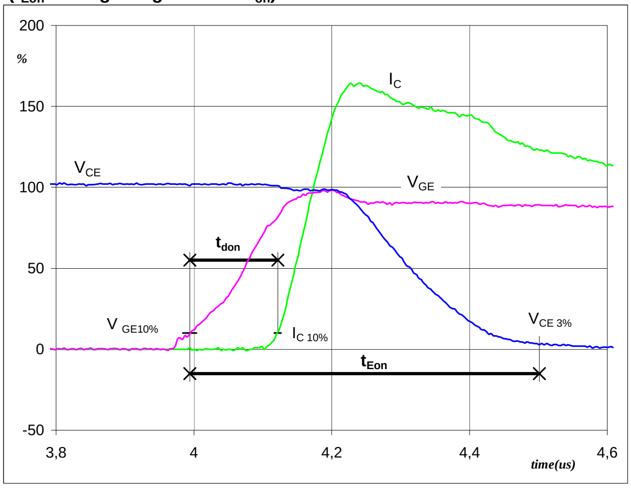
Turn-off Switching Waveforms & definition of t_{doff}, t_{Eoff}
(t_{Eoff} = integrating time for E_{off})



V_{GE} (0%) =	-15	V
V_{GE} (100%) =	15	V
V_C (100%) =	600	V
I_C (100%) =	25	A
t_{doff} =	0,32	µs
t_{Eoff} =	0,74	µs

Figure 2 Output inverter IGBT

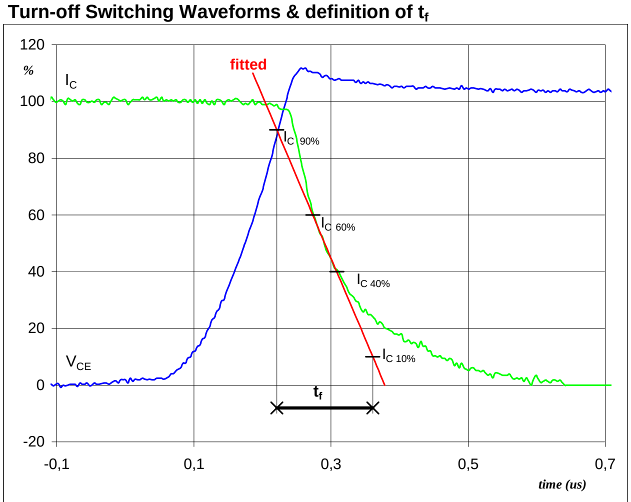
Turn-on Switching Waveforms & definition of tdon, t_{Eon}
(t_{Eon} = integrating time for E_{on})



V_{GE} (0%) =	-15	V
V_{GE} (100%) =	15	V
V_C (100%) =	600	V
I_C (100%) =	25	A
t_{don} =	0,13	µs
t_{Eon} =	0,51	µs

Figure 3 Output inverter IGBT

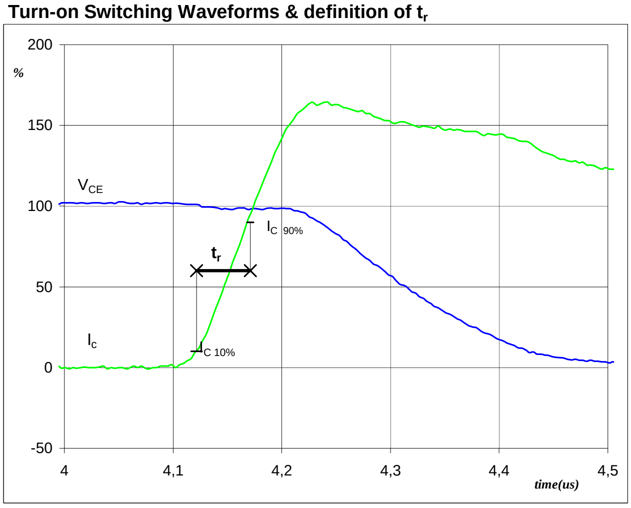
Turn-off Switching Waveforms & definition of t_f



V_C (100%) =	600	V
I_C (100%) =	25	A
t_f =	0,14	µs

Figure 4 Output inverter IGBT

Turn-on Switching Waveforms & definition of t_r

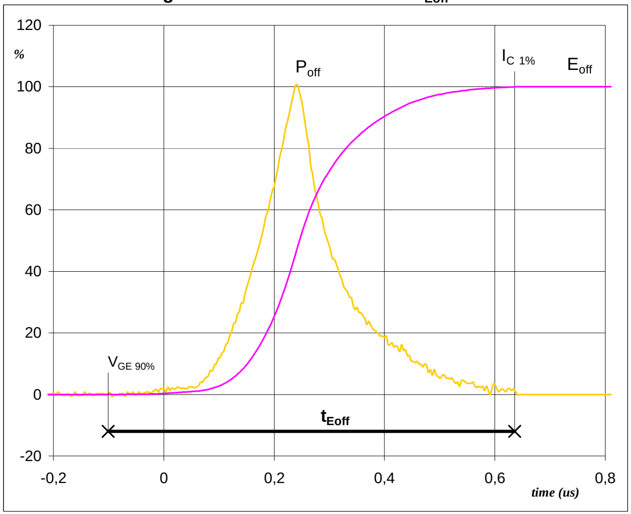


V_C (100%) =	600	V
I_C (100%) =	25	A
t_r =	0,05	µs

Switching Definitions Output Inverter

Figure 5 Output inverter IGBT

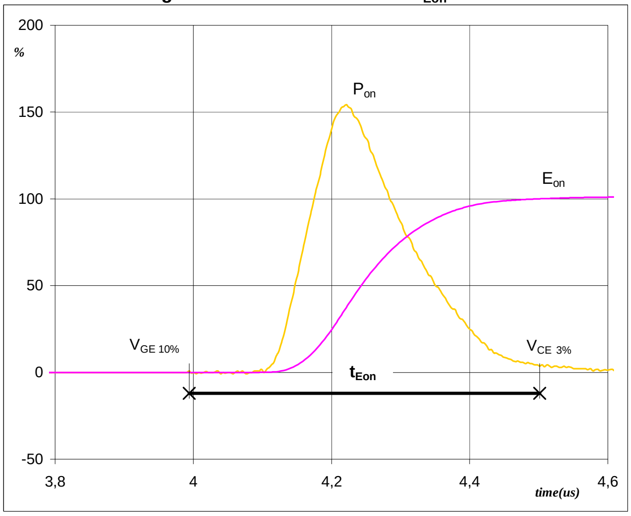
Turn-off Switching Waveforms & definition of t_{Eoff}



P_{off} (100%) =	14,93	kW
E_{off} (100%) =	2,45	mJ
t_{Eoff} =	0,74	Ős

Figure 6 Output inverter IGBT

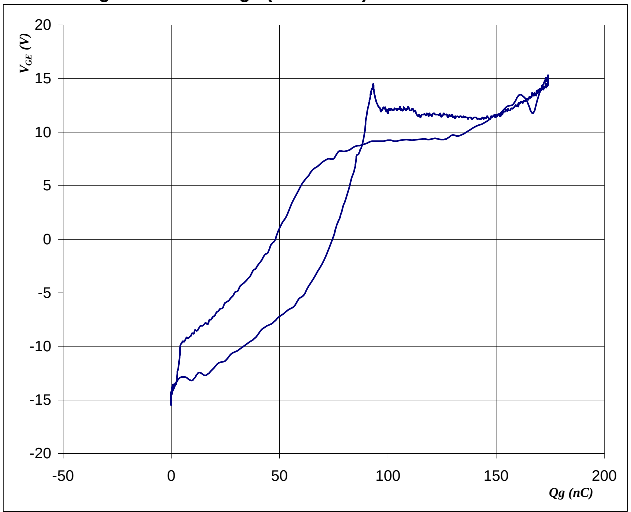
Turn-on Switching Waveforms & definition of t_{Eon}



P_{on} (100%) =	14,93	kW
E_{on} (100%) =	3,77	mJ
t_{Eon} =	0,51	Ős

Figure 7 Output inverter FWD

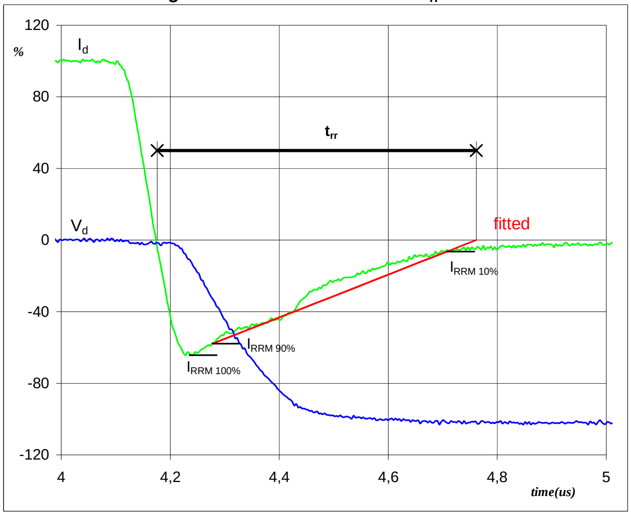
Gate voltage vs Gate charge (measured)



V_{GEoff} =	-15	V
V_{GEon} =	15	V
V_C (100%) =	600	V
I_C (100%) =	25	A
Q_g =	173,95	nC

Figure 8 Output inverter IGBT

Turn-off Switching Waveforms & definition of t_{rr}

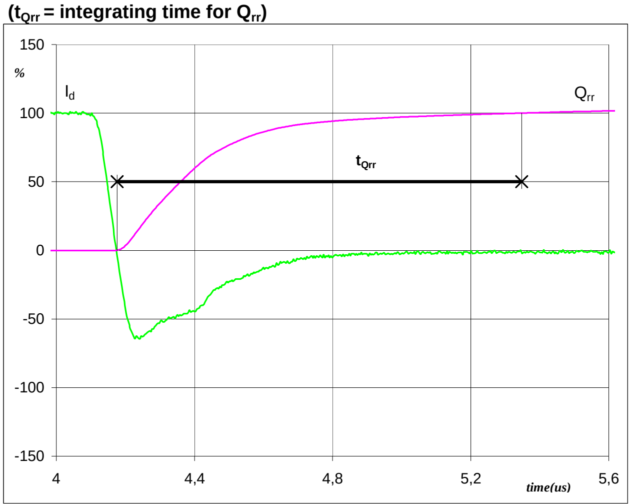


V_d (100%) =	600	V
I_d (100%) =	25	A
I_{RRM} (100%) =	-16	A
t_{rr} =	0,56	Ős

Switching Definitions Output Inverter

Figure 9 Output inverter FWD

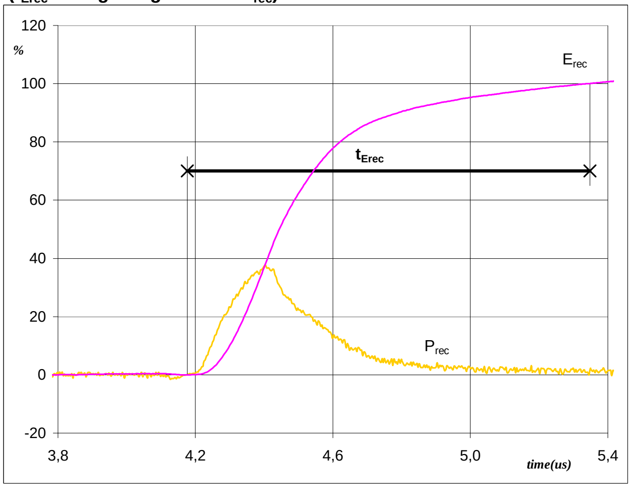
Turn-on Switching Waveforms & definition of t_{Qrr}
(t_{Qrr} = integrating time for Q_{rr})



I_d (100%) =	25	A
Q_{rr} (100%) =	4,68	ČC
t_{Qrr} =	1,17	Čs

Figure 10 Output inverter FWD

Turn-on Switching Waveforms & definition of t_{Erec}
(t_{Erec}= integrating time for E_{rec})



P_{rec} (100%) =	14,93	kW
E_{rec} (100%) =	1,74	mJ
t_{Erec} =	1,17	Čs

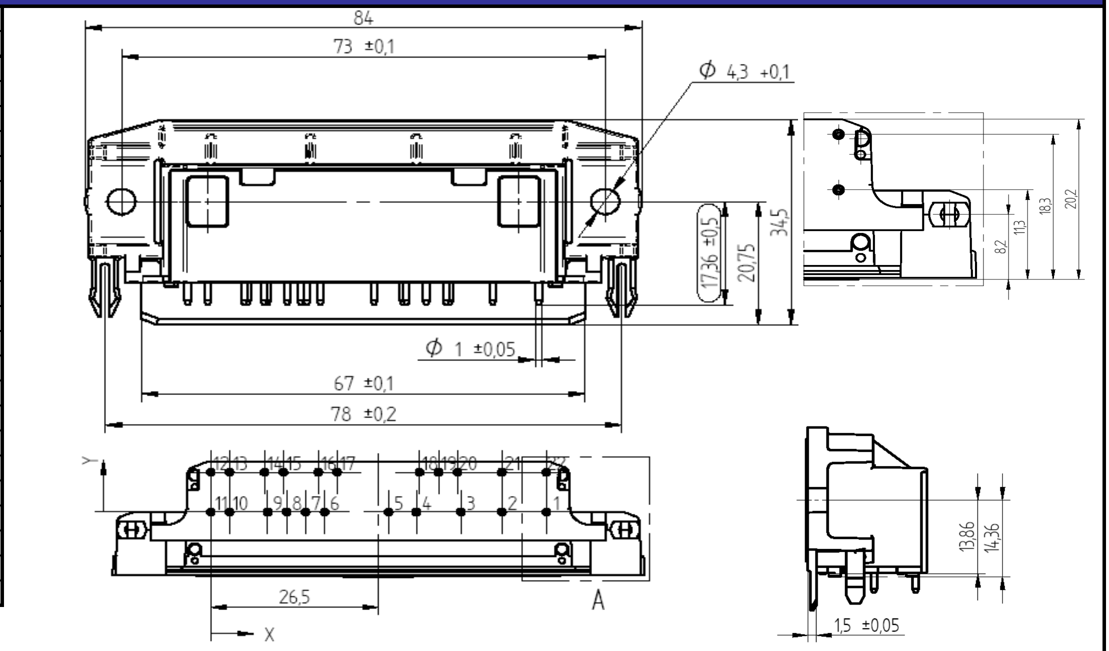
Ordering Code and Marking - Outline - Pinout

Ordering Code & Marking

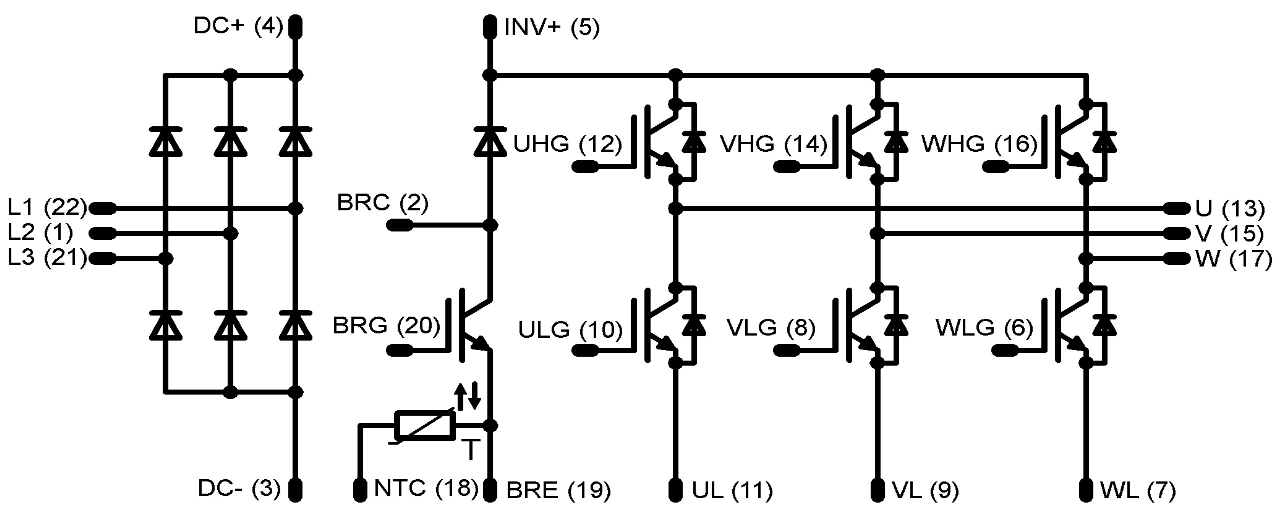
Version	Ordering Code	in DataMatrix as	in packaging barcode as
without thermal paste	V23990-P630-A44-PM	P630-A44	P630-A44

Outline

Pin table		
Pin	X	Y
1	53	0
2	46	0
3	39,5	0
4	32,5	0
5	28,1	0
6	18	0
7	15	0
8	12	0
9	9	0
10	3	0
11	0	0
12	0	7
13	3	7
14	8,5	7
15	11,5	7
16	17	7
17	20	7
18	33	7
19	36	7
20	39	7
21	46	7
22	53	7



Pinout



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2. A critical component is any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.